

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"20040056338"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:03
S2	3	"6639308"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 09:40
S3	1	"6388336".PN.	USPAT	OR	OFF	2004/10/06 09:45
S4	2809	@ad<="19991216" and (257/666). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S5	238	@ad<="19991216" and (257/672). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S6	1553	@ad<="19991216" and (257/676). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S7	673	@ad<="19991216" and (257/e23. 039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S8	1127	@ad<="19991216" and (257/692). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S9	200	@ad<="19991216" and (438/111). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:06
S10	570	@ad<="19991216" and (438/123). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:06
S11	348	@ad<="19991216" and (257/670). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22

S12	571	@ad<="19991216" and (257/677). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S13	99	@ad<="19991216" and (257/e23. 141).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:10
S14	915	@ad<="19991216" and (257/e23. 043).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11
S15	52	@ad<="19991216" and (257/e23. 045).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11
S16	24	@ad<="19991216" and (257/e23. 05).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11
S17	330	@ad<="19991216" and (257/e23. 052).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:12
S18	303	@ad<="19991216" and (257/e23. 066).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:12
S19	83	@ad<="19991216" and (257/666). ccls. and 'lead frame' and 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:13
S20	559	@ad<="19991216" and (361/813). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:21
S21	76	@ad<="19991216" and 'lead frame' and 'tie bar' and 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:58
S22	2	@ad<="19991216" and 'chip' same 'lead frame' and 'various' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:01

S23	2	("6239487").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/06 11:00
S24	2	@ad<="19991216" and 'lead frame' and 'various' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:37
S25	164	@ad<="19991216" and 'lead frame' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S26	57	@ad<="19991216" and 'lead frame' same 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S27	37	@ad<="19991216" and 'semiconductor package' and 'lead frame' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 08:58
S28	23	@ad<="19991216" and 'lead frame' same 'variable' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S29	108	@ad<="19991216" and 'lead frame' with 'flange'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S30	120	@ad<="19991216" and 'semiconductor package' and 'leadframe' with 'step'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:29
S31	1	@ad<="19991216" and 'leadframe' and 'various' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:37
S32	31	@ad<="19991216" and 'leadframe' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S33	11	@ad<="19991216" and 'leadframe' same 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38

S34	5	@ad<="19991216" and 'leadframe' same 'variable' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S35	11	@ad<="19991216" and 'leadframe' with 'flange'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 08:45
S36	1	"4258381".PN.	USPAT	OR	OFF	2004/10/06 12:34
S37	1	"5065223".PN.	USPAT	OR	OFF	2004/10/06 12:34
S38	1	"5703407".PN.	USPAT	OR	OFF	2004/10/06 12:34
S39	1	"5753977".PN.	USPAT	OR	OFF	2004/10/06 12:36
S40	1	"5834830".PN.	USPAT	OR	OFF	2004/10/06 12:37
S41	1	"6060768".PN.	USPAT	OR	OFF	2004/10/06 12:37
S42	1	"6143981".PN.	USPAT	OR	OFF	2004/10/06 12:38
S43	1	"6229200".PN.	USPAT	OR	OFF	2004/10/06 12:38
S44	1	"6242281".PN.	USPAT	OR	OFF	2004/10/06 12:39
S45	1	"6294100".PN.	USPAT	OR	OFF	2004/10/06 12:39
S46	1	"6355502".PN.	USPAT	OR	OFF	2004/10/06 12:40
S47	1	"6355502".PN.	USPAT	OR	OFF	2004/10/06 12:40
S48	1	"6020625".PN.	USPAT	OR	OFF	2004/10/06 12:59
S49	1	"6020625".PN.	USPAT	OR	OFF	2004/10/06 12:59
S50	1	"5949138".PN.	USPAT	OR	OFF	2004/10/06 13:00
S51	1	"5929514".PN.	USPAT	OR	OFF	2004/10/06 13:01
S52	1	"5898220".PN.	USPAT	OR	OFF	2004/10/06 13:02
S53	3	("5929513").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/01/05 08:36
S54	1	"5227662".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:37
S55	1	"6388336".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:40
S56	1	"6355502".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:40
S57	1	"6294100".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:40
S58	1	"6242281".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:40
S59	1	"6229200".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:41
S60	1	"6143981".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:41
S61	1	"6060768".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:42

S62	1	"5834830".PN.	USPAT; USOCR	OR	ON	2005/01/05 08:43
-----	---	---------------	-----------------	----	----	------------------

S63	563	(024122" 0068" 65" 3734660" 189342" 1464" 24" 4707724" 756080" 2246" 03" 5018003" 057900" 0039" 52" 5157480" 172214" 0809" 31" 5258094" 277972" 1849" 64" 5358905" 391439" 4299" 57" 5474958" 508556" 8076" 57" 5592019" 595934" 5222" 47" 5646831" 665996" 9135" 07" 5736432" 753977" 6798" 77" 5817540" 834830" 6911" 82" 5886398" 900676" 9053" 79" 5969426" 977613" 1314" 29" 6291881" 018189" 1279" 30" 6075284" 087722" 8174" 184465" 6184573" 6194777" 619	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 08:58
BEST AVAILABLE COPY						
Search History 9/15/05 8:56:58 AM Page 6 C:\Documents and Settings\user\My Documents\ASIT\Workspaces\Packaging, Flip Chip, BGA, Solder Ball, Bonding Pad, Testing, PC						

S64	42	@ad<="20001013" and 'semiconductor package' and 'lead frame' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S65	1	"6002178".PN.	USPAT; USOCR	OR	ON	2005/01/05 09:20
S66	1	"5959347".PN.	USPAT; USOCR	OR	ON	2005/01/05 09:20
S67	1	"5952725".PN.	USPAT; USOCR	OR	ON	2005/01/05 09:20
S68	1	"5917242".PN.	USPAT; USOCR	OR	ON	2005/01/05 09:20
S69	1	"5793108".PN.	USPAT; USOCR	OR	ON	2005/01/05 09:21
S70	2811	@ad<="19991216" and (257/666). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S71	238	@ad<="19991216" and (257/672). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S72	1554	@ad<="19991216" and (257/676). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S73	674	@ad<="19991216" and (257/e23. 039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S74	1128	@ad<="19991216" and (257/692). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S75	349	@ad<="19991216" and (257/670). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S76	571	@ad<="19991216" and (257/677). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S78	184	@ad<="20001013" and 'lead frame' and ('chip' or 'IC') and 'seal' and 'tie bar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:29

S79	10	@ad<="20001013" and 'lead frame' and ('chip' or 'IC') and 'seal' and 'tie bar' and 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:25
S80	184	@ad<="20001013" and 'lead frame' and ('chip' or 'IC') and 'seal' and 'tie bar' and 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:00
S81	5	@ad<="20001013" and 'peripheral tie bar' with 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:02
S83	23	@ad<="20001013" and 'tie bar' with 'lead' with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:08
S84	0	@ad<="20001013" and 'lead fram' with 'lead' with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:06
S85	361	@ad<="20001013" and 'lead frame' with 'lead' with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:06
S86	2148	@ad<="20001013" and 'tie bar' with 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:08
S87	1576	@ad<="20001013" and 'lead frame' same 'tie bar' with 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:09
S88	1385	@ad<="20001013" and 'lead frame' with 'tie bar' with 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 11:32
S89	7	@ad<="20001013" and 'micro lead frame'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 10:31
S90	75	@ad<="20001013" and 'lead frame' with 'tiebar' with 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 12:10

S91	0	@ad<="20001013" and 'lead on chip' same 'tiebar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 12:11
S93	0	@ad<="20001013" and 'lead on chip' and 'tiebar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 12:13
S94	2	@ad<="20001013" and 'lead-on-chip' and 'tiebar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 08:22
S95	1	"5648682".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:13
S96	1	"5616953".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:15
S97	1	"5583372".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:15
S98	1	"5559366".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:15
S99	1	"5559366".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:16
S10 0	1	"5442231".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:16
S10 1	1	"5357139".PN.	USPAT; USOCR	OR	ON	2005/01/05 12:16
S10 2	44	@ad<="20001013" and 'lead-on-chip' and 'tie bar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 08:22
S10 3	1	"5677566".PN.	USPAT; USOCR	OR	ON	2005/03/28 08:40
S10 4	1	"5668405".PN.	USPAT; USOCR	OR	ON	2005/03/28 08:40
S10 5	1	"5663594".PN.	USPAT; USOCR	OR	ON	2005/03/28 08:41
S10 6	1	"5157480".PN.	USPAT; USOCR	OR	ON	2005/03/28 08:41
S10 7	782	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 08:46
S10 8	10	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die' and 'sealing material'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:06

S109	0	@ad<="19991216" and 'lead frame' and 'tie bar' and 'lead on chip'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 08:48
S110	66	@ad<="19991216" and 'lead frame' and 'tie bar' and 'LOC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:01
S111	11	@ad<="19991216" and 'lead frame' and 'tie bar' and 'COL'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:01
S112	240	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die' and 'sealing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:06
S113	19354	@ad<="20040113" and (257/690).ccls. or (257/730).ccls. or (257/787)".ccls" or (257/686).ccls. or (257/783).ccls. or (257/777).ccls. or (257/696).ccls. or (257/676).ccls. or (257/707).ccls. or (257/675).ccls. or (257/666).ccls. (257/692).ccls. or (257/711).ccls. (257/784).ccls. or (257/731).ccls. or (257/106).ccls. or (438/106).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:34
S114	6	@ad<="20040113" and 'chip' and 'tie bars' and 'chip paddle' and 'lead' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:42
S115	22	@ad<="20040113" and 'chip' and 'tie bars' and 'chip pad' and 'lead' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:35
S116	188	@ad<="20040113" and 'chip' and 'tie bar' and ('chip paddle' or 'die pad') and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:51
S117	1	"6198171".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:45
S118	1	"6075284".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:46
S119	1	"6025640".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:46
S120	1	"6184580".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:46
S121	1	"5926371".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:46

S12 2	1	"6177721".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:47
S12 3	1	"6072239".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:47
S12 4	1	"6002181".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:47
S12 5	1	"5904497".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:48
S12 6	1	"5705851".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:49
S12 7	83	'Siliconware' and 'quad flat' with 'package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:52
S12 8	183	@ad<="20040113" and 'chip' and 'tie bar' and 'die pad' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:54
S12 9	6	@ad<="20040113" and 'chip' and 'tie bar' and 'chip paddle' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:51
S13 0	10	'Siliconware' and 'quad flat' with 'package' and 'tie bar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:52
S13 1	177	@ad<="20040113" and 'chip' and 'tie bar' and 'die pad' and 'bonding pad' and 'wire'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:54
S13 2	154	@ad<="20040113" and 'chip' and 'tie bar' and 'die pad' and 'bonding pad' and 'wire' and 'lead frame'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:54
S13 3	1	"6265771".PN.	USPAT; USOCR	OR	ON	2005/05/05 09:56